

Material Content Data Sheet

RoHS

Sales Product Name	BTS141TC	**Issued**	17. February 2022
MA#	MA005698296		
Package	PG-TO263-3-2	**Weight***	1543.71 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.454	0.03	0.03	294	294
chip_2	inorganic material	silicon	7440-21-3	7.797	0.51	0.51	5051	5051
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		197	
	non noble metal	copper	7440-50-8	304.026	19.69	19.72	196946	197202
wire	non noble metal	aluminium	7429-90-5	1.750	0.11	0.11	1134	1134
encapsulation	organic material	carbon black	1333-86-4	7.319	0.47		4741	
	inorganic material	antimonytrioxide	1309-64-4	15.304	0.99		9914	
	plastics	brominated resin	-	17.300	1.12		11207	
	plastics	epoxy resin	-	126.427	8.19		81898	
	inorganic material	silicondioxide	60676-86-0	499.053	32.33	43.10	323283	431043
leadfinish	non noble metal	tin	7440-31-5	9.657	0.63	0.63	6256	6256
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	148	149
solder	non noble metal	tin	7440-31-5	0.109	0.01		71	
	noble metal	silver	7440-22-4	0.136	0.01		88	
	non noble metal	lead	7439-92-1	5.213	0.34	0.36	3377	3536
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	101	101
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		107	
	non noble metal	iron	7439-89-6	0.548	0.04		355	
	non noble metal	copper	7440-50-8	547.666	35.47	35.52	354772	355234
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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